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							REVISONS			
							REV	DESCRIPTION	APPROVED	DATE
							NOTES:			
							UNLESS OTHERWISE SPECIFIED			
							1. DIMENSIONS ARE IN INCHES (EXCEPT WHERE NOTED).			
							MATERIAL: (USE CHECKED ITEMS FOR MATERIAL)			
							2. BOARD MATERIAL:			
							(X) ISOLA 370HR OR EQUIVALENT			
							() ISOLA-FR408HR OR EQUIVALENT			
							() NELCO-4000-13			
							() MEGTRON 6			
							() ROGERS 4350B			
							() ROGERS 4003C			
							() OTHER _____			
							3. THE PCB SHALL BE FABRICATED TO IPC-6012, TYPE X, CLASS 2.			
							WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2, CURRENT REVISIONS.			
							4. BOARD MATERIAL & CONSTRUCTION SHALL MEET THE REQUIREMENTS OF UL796 WITH FLAMMABILITY RATING OF 94V-0.			
							5. OVERALL BOARD THICKNESS REFER TO LAMINATION DIAGRAM. TOLERANCE APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES. IT IS TO BE MEASURED FROM TOP PCB METAL TO BOTTOM PCB METAL UNLESS OTHERWISE SPECIFIED.			
							6. BOW & TWIST NOT TO EXCEED 0.0075 IN. (0.75%) PER LINEAR INCH.			
							BOW & TWIST SHOULD BE MEASURED PER IPC-TM-650, METHOD 2.4.22.			
							TOOLING:			
							7. PHOTO ETCH CIRCUITRY PER ENCLOSED GERBER RS274X OR ODB++ FORMAT FILE.			
							DRILL LOCATION AND SIZE CONTROLLED BY EXCELLON CNO DRILL FILE.			
							8. IMPEDANCE REQUIREMENTS: IF NO STACKUP IS DEFINED, THE VENDOR IS ALLOWED TO ADJUST THE DIELECTRIC THICKNESS AND TRACE WIDTHS TO MEET THE IMPEDANCE REQUIREMENT. IF SPECIFIED, VENDOR MUST FOLLOW AND MEET THE REQUIREMENTS LISTED IN THE IMPEDANCE TABLE. ANY ADJUSTMENTS MADE TO THE DEFINED STACKUP, TRACE WIDTH & SPACING THAT IMPACT THE REQUIREMENTS MUST HAVE WRITTEN APPROVAL FROM MAXIM.			
							9. ALL TRACES FILLETED OPTION TO ENHANCE RELIABILITY AT PAD JUNCTIONS WHERE SPACING PERMITS. UNLESS OTHERWISE SPECIFIED:			
							() FILLETED			
							(X) NOT FILLETED			
							10. LAYER TO LAYER REGISTRATIONS SHALL BE WITHIN .003 INCHES.			
							LEGEND TO LEGEND +/- 0.007 INCHES			
							11. FINISHED COPPER WEIGHT/THICKNESS:			
							(X) REFER TO LAMINATION DIAGRAM FOR FINISHED COPPER WEIGHT/THICKNESS REQUIREMENTS.			
							THE STARTING COPPER WEIGHT/THICKNESS CAN VARY AS LONG AS THE FINISHED COPPER WEIGHT/THICKNESS IS NOT LESS THAN THE SPECIFIED VALUE, UNLESS OTHERWISE SPECIFIED.			
							() OTHER _____			
							SURFACE FINISH:			
							12. USE CHECKED ITEMS FOR PLATING			
							() ELECTRODEPOSITED HARD GOLD PLATE, TYPE 1 (99.7% MIN GOLD), GRADE C			
							(KNOOP HARDNESS 130-200), CLASS 1 (50-100 MICRO INCHES THICK) IN ACCORDANCE WITH MIL-G-45204C.			
							GENERAL SURFACING REQUIREMENTS MUST MEET ANSI/IPC-A-600(CURRENT REV) SECTION 4.0.			
							CLASS 3 (50-100 MICROINCHES THICK) OVER ELECTRODEPOSITED NICKEL PLATE			
							IN ACCORDANCE WITH ANSI/IPC-A-600D, SECTION 4.0, CLASS 3 (200-400 MICROINCHES THICK).			
							(X) FINISH CONDUCTOR SURFACES: IMMERSION GOLD, 1.58-3.94 MICRO INCHES OVER			
							118-236 MICRO INCHES MINIMUM OF ELECTROLESS NICKEL.			
							() FINGERS TO BE GOLD PLATED.			
							() LEAD FREE AND ROHS COMPLIANT PLATING (DO NOT USE OSP)			
							() FINISH CONDUCTOR ENPIG: GREATER THAN 1.2 MICRO INCHES IMMERSION GOLD OVER			
							2-12 MICRO INCHES ELECTROLESS PALLADIUM OVER			
							118-236 MICRO INCHES MINIMUM OF ELECTROLESS NICKEL IN ACCORDANCE WITH IPC-4556, SECTION 3			
							() OTHER _____			
							13. DRILL SIZES ARE FINISHED HOLE SIZES. ALL HOLES SHALL BE LOCATED WITHIN .005 DTP.			
							MINIMUM BARREL PLATING OF .001 IN, PLATED HOLES SHALL NOT BE ROUGH OR IRREGULAR SO AS TO HINDER PROPER SOLDER WICKING. BARREL RELIEF ON SOLDERMASK ALLOWED ON UNFILLED VIA IN PAD HOLES.			
							SOLDERMASK:			
							14. SOLDERMASK OVER BARE COPPER OR BARE GOLD (BOTH SIDES) WITH LIQUID PHOTO IMAGEABLE (LPI) INK			
							(X) CUSTOM MAXIM TEAL SOLDER MASK. PANTONE #326C.			
							() OTHER _____			
							SILKSCREEN:			
							15. APPLY SILKSCREEN USING A NON-CONDUCTIVE EPOXY INK			
							(X) WHITE			
							() OTHER _____			
							16. VENDOR LOGO & DATE CODE REQUIREMENT. DATE CODE FORMAT MUST BE YYYY ONLY			
							(X) PLACE ON BOTTOM LEGEND LAYER. IF NO BOTTOM LEGEND SUPPLIED, CREATE BOTTOM LEGEND LAYER TO ADD.			
							() PLACE ON TOP LEGEND LAYER. IF NO TOP LEGEND SUPPLIED,CREATE TOP LEGEND LAYER TO ADD.			
							() OTHER _____			
							TESTING:			
							17. FINAL ELECTRICAL TEST TO BE PERFORMED USING PROVIDED IPC-D-356A NETLIST OR ODB++ FORMAT FILE.			
							(REQUIRED UNLESS OTHERWISE SPECIFIED IN QUOTE)			
							THE PCB SHALL HAVE A VERIFICATION STAMP.			
							18. A TIME DOMAIN REFLECTOMETER REPORT FOR EACH IMPEDANCE CONTROLLED LAYER AND A CERTIFICATE OF COMPLIANCE SHALL BE PROVIDED BY VENDOR AT TIME OF SHIPMENT. INSTANCES WHERE TDR TESTING CAN'T BE PERFORMED BECAUSE THE TRACE LENGTH IS TOO SHORT ON THE OUTER LAYERS AT THE PIN ESCAPES IS ACCEPTABLE. ALL OTHER INSTANCES MUST BE REPORTED.			
							MISCELLANEOUS:			
							19. IF PRESENT, ALL BLIND/BURIED VIAS WITH AN ASPECT RATIO <1:1 TO BE PLATED SHUT WITH COPPER WHEN USED AS VIA-IN PAD OR AS A STACKED VIA. BLIND/BURIED VIAS WITH AN ASPECT RATIO >1:1 TO BE FILLED WITH NON-CONDUCTIVE EPOXY, UNLESS OTHERWISE SPECIFIED.			
							20. FOR ALL DRILL INFORMATION REFER TO DRILL CHART.			
							() NON-CONDUCTIVE EPOXY. FILL AND CAP ALL 0.00XX INCH DRILLED VIAS.			
							() SILVER. FILL AND CAP ALL 0.00XX INCH DRILLED VIAS.			
							21. FINISHED SURFACE CONTACTS AND FILLED VIAS TO BE FREE OF ANY PITS, SCRATCHES PROBE MARKS OR OTHER DEFORMITIES THAT COULD EFFECT THE APPEARANCE AND PERFORMANCE OF THE CONTACT SURFACE. CONTACTS ARE TO BE AS FLAT AS POSSIBLE, NOT TO EXCEED +/- 0.001" OF FLATNESS.			
							22. THEIEVING:			
							() SUPPLIER MAY ADD THEIEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN.			
							(X) SUPPLIER MAY NOT ADD THEIEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN.			
							23. PEMNUT			
							() PEMNUTS TO BE INSTALLED BY FABRICATOR..			
							() PEMNUTS NOT TO BE INSTALLED BY FABRICATOR.			
							(X) NOT APPLICABLE.			
							TOLERANCES UNLESS OTHERWISE SPECIFIED			
							FRACTIONS DECIMALS ANGLES			
							+/- $\frac{\quad}{\quad}$.XX +/- .01 +/- $\frac{\quad}{\quad}$			
							.XXX +/- .005			
							MATERIAL:			
							SEE NOTES			
							DRAWN BY:DN DATE: 01/16/2020			
							CHECKED BY: DATE:			
							APPR. BY: DATE:			
							APPR. BY: DATE:			
							MAX25300_EVKIT_A			
							HARDWARE NUMBER: XX-XXXX-XXX			
							NOT TO SCALE			
							SHEET 1 OF 1			

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